

## FACT SHEET

# ICT-TC-GFSP-SF-HP-5031



High-performance, silicon-free gap filler pad with 9.00 W/m·K thermal conductivity, excellent insulation, and low outgassing.



5 GAP FILLERS, PADS, SPACERS, SOFT-ULTRA-SOFT GEL SILICONE-FREE

## DESCRIPTION

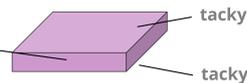
The **ICT-TC-GFSP-SF-HP-5031 Series** is the latest product generation of silicone-free, high-performance, thermally conductive gap filler pads from ICT SUEDWERK. These product series are composed of a silicone-free, resin-based thermoplastic elastomer (TPE).

The **ICT-TC-GFSP-SF-HP-5031 Series** is characterized by very high thermal conductivity of **9.00 W/m·K** combined with outstanding electrical insulation properties, based on advanced composite material technologies, while also maintaining silicone's superior heat resistance. This premium product has no low-molecular siloxane volatilization whatsoever, and very low total volatile gas.

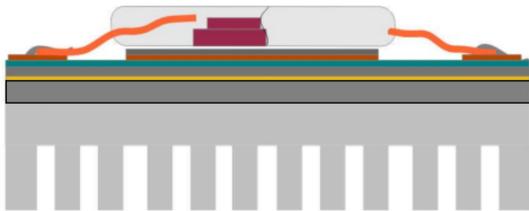
The **ICT-TC-GFSP-SF-HP-5031 Series** is soft, flexible, and exhibits good springback behavior. Its low hardness ensures excellent compressibility, while its stress relaxation properties, low specific weight, and very good price-performance ratio are what make this material stand out.

The **ICT-TC-GFSP-SF-HP-5031 Series** is available in material thicknesses ranging from 0.5 to 10.00 mm. Additional thicknesses are available upon request.

## TYPICAL PROPERTIES

Product Configuration	Material structure
ONE-LAYER TYPE SILICONE FREE RESIN BASED THERMOPLASTIC ELASTOMER	
<b>Color</b>	Pink
<b>Density</b>	3.4 g/cm <sup>3</sup>
<b>Thermal conductivity</b>	9 W/m <sup>2</sup> K
<b>Thermal impedance @ 20 psi</b>	≤ 0.166 C°-in <sup>2</sup> /W
<b>Volume resistivity</b>	≥ 1,00 × 10 <sup>10</sup> Ω/m
<b>Dielectric breakdown voltage</b>	8 kV/mm
<b>Hardness (Shore 00)</b>	50
<b>Compressibility @ 20psi</b>	35 %

## IMAGES



Product Profile (schematic image)



ICT-TC-GFSP-SF-HP-5031

Image may differ from product

## FEATURES

- › Made from a silicone-free, resin-based material
- › High thermal performance: **9.0 W/m·K thermal conductivity / Rth 0.166 °C-in<sup>2</sup>/W (@ 20 psi)**
- › Tacky surface for excellent surface wet-out
- › Soft and flexible, with very good compressibility
- › Effective performance under low contact pressure
- › Excellent electrical insulation (UL 94 V-0 certified)
- › The ICT-TC-GFSP-SF-HP-5031 Series is environmentally compliant with RoHS 2.0, halogen-free, and REACH standards

## DELIVERY FORMS / APPLICATIONS

- Applicable to optical and sensitive electronic components
- Optoelectronic industry applications
- Viscous surface for enhanced adhesion
- HDDS / Netcom products
- Electric vehicles (EVs) and new energy battery applications
- 5G base stations and infrastructure
- Wearable devices and related electronics

ICT4TIM Partners



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